

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)
TRANSMITTAL FORM

Attorney Docket No. TI-31373

Assistant Commissioner for Patents
Washington, D. C. 20231



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Date of Deposit: December 26, 2001. I hereby certify that this
paper is being deposited with the U.S. Postal Service Express Mail
Post Office to Addressee Service under 37 CFR 1.10 on the
date shown above and is addressed to the Assistant Commissioner
for Patents, Washington, D.C. 20231.

Emily C. Chant

Date

Sir:

Transmitted herewith for filing is the
patent application of:

Inventor(s): Gary P. Morrison
Darvin R. Edwards
Leslie Stark

For: **CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR FOR VERTICAL
ASSEMBLY ON SUBSTRATES**

Enclosed are:

- 5 Sheets of formal drawings and 28 pages of Specification (including Abstract)
x A Declaration/Power of Attorney
— Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

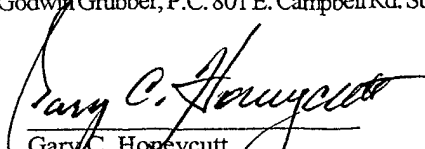
This application claims priority under 35 U.S.C. § 119 based upon **Provisional Patent
Application number 60/258,525 filed 12/28/2000.**

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 740.00
Total Claims	23	-20 =	3	X \$18 =	\$54.00
Independent Claims	6	- 3 =	3	X \$84 =	\$252.00
Total Filing Fee					\$1046.00

Please charge **Deposit Account No. 20-0668** in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. **This form is submitted in triplicate.**

All correspondence related to this application may be addressed to the undersigned at Godwin Grubber, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: December 26, 2001


Gary C. Honeycutt
Registration No. 20,250